

A

Heatsinks for PGAs and BGAs

B

C

D

E

F

G

H

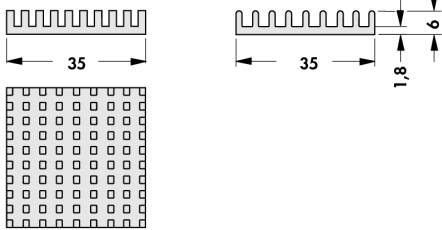
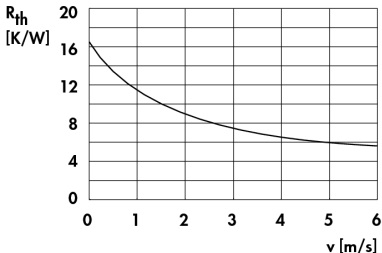
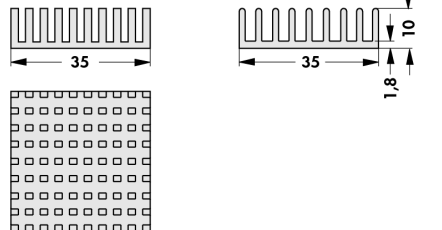
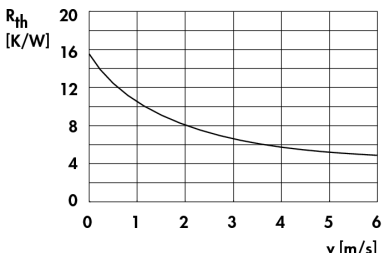
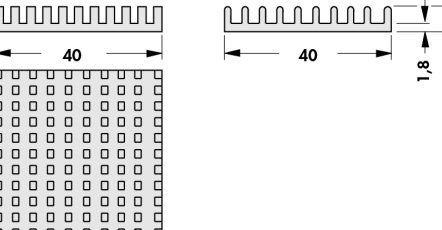
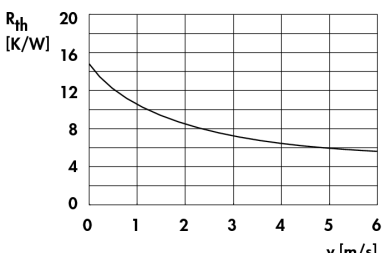
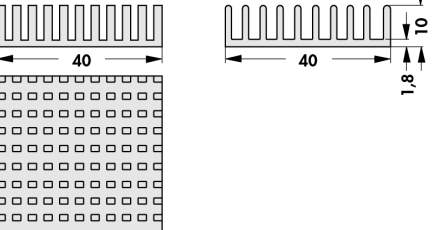
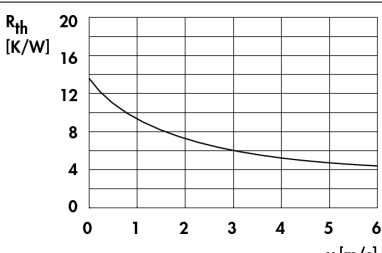
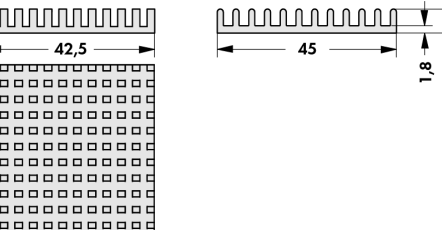
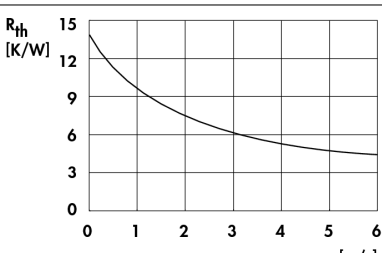
I

K

L

M

N

art. no. ICK BGA 35 x 35 WLF ... 35 x 35		
art. no. ICK BGA 35 x 35 x 10 WLF ... 35 x 35		
art. no. ICK BGA 40 x 40 WLF ... 40 x 40		
art. no. ICK BGA 40 x 40 x 10 WLF ... 40 x 40		
art. no. ICK BGA 42,5 x 45 WLF ... 42,5 x 45		

B 15

Thermal conduct. foil WLFT 404/405 → E 5
 Thermal conductive glue → E 14
 Thermal conductive paste → E 12
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27
 Mounting material for semiconduct. → E 34 - 38
 Hole pattern → A 21
 Technical introduction → A 2 - 7